Tender of 10-year RMB HKSAR Institutional Government Bonds through re-opening to be held on Thursday, 12 November 2026

The Hong Kong Monetary Authority (HKMA), as representative of the Hong Kong Special Administrative Region Government (HKSAR Government), announced today (6 November) that a tender of 10-year RMB institutional Government Bonds (Bonds) through the re-opening of existing 10-year Government Bond issue 10GB3505001 under the Infrastructure Bond Programme will be held on Thursday, 12 November 2026, for settlement on Monday, 16 November 2026.

An additional amount of RMB1.5 billion of the outstanding 10-year Bonds (issue no. 10GB3505001) will be on offer. The Bonds will mature on 15 May 2035 and will carry interest at the rate of 2.29% per annum payable semi-annually in arrear. The Indicative Pricings of the Bonds on 6 November 2026 are 104.18 with a semi-annualised yield of 1.760%.

Tender is open only to Primary Dealers appointed under the Infrastructure Bond Programme. Anyone wishing to apply for the Bonds on offer can do so through any of the Primary Dealers on the latest published list, which can be obtained from the Hong Kong Government Bonds website at https://www.hkgb.gov.hk. Each tender must be for an amount of RMB50,000 or integral multiples thereof.

Tender results will be published on the HKMA's website, the Hong Kong Government Bonds website, Bloomberg (GBHK <GO>) and Refinitiv (IBPGSBPINDEX). The publication time is expected to be no later than 3:00 pm on the tender day.

Hong Kong Monetary Authority
6 November 2026

HKSAR INSTITUTIONAL GOVERNMENT BONDS TENDER INFORMATION

Tender information of 10-year RMB HKSAR Institutional Government Bonds:-

Issue Number	:	10GB3505001
Stock Code	:	85024 (HKGB2.29 3505-R)
Tender Date and Time	:	Thursday, 12 November 2026 9:30 am to 10:30 am
Issue and Settlement Date	:	Monday, 16 November 2026
Amount on Offer	:	RMB1.5 billion
Maturity	:	10 years
Remaining maturity	:	Approximately 8.50 years
Maturity Date	:	Tuesday, 15 May 2035
Interest Rate	:	2.29% p.a. payable semi-annually in arrear
Interest Payment Dates	:	15 May and 15 November in each year, commencing on the Issue Date up to and including the Maturity Date, subject to adjustment in accordance with the terms of the Institutional Issuances Information Memorandum of the Infrastructure Bond Programme and Government Sustainable Bond Programme (Information Memorandum) published on the Hong Kong Government Bonds website.
Method of Tender	:	Competitive tender
Tender Amount	:	Each competitive tender must be for an amount of RMB50,000 or integral multiples thereof. Any tender applications for the Bonds must be submitted through a Primary Dealer on the latest published list. The accrued interest to be paid by successful bidders on the issue date (16 November 2026) for the tender amount is RMB0.00 per minimum denomination of RMB50,000. (The accrued interest to be paid for tender amount exceeding RMB50,000 may not be exactly equal to the figures calculated from the accrued interest per minimum denomination of RMB50,000 due to rounding).

Other Details	:	Please see the Information Memorandum available on the Hong Kong Government Bonds website or approach Primary Dealers.
Expected commencement date of dealing on the Stock Exchange of Hong Kong Limited	:	The tender amount is fully fungible with the existing 10GB3505001 (Stock code: 85024) listed on the Stock Exchange of Hong Kong.
Use of Proceeds	:	The Bonds will be issued under the institutional part of the Infrastructure Bond Programme. Proceeds will be invested in infrastructure projects in accordance with the Infrastructure Bond Framework published on the Hong Kong Government Bonds website.

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